

4222021/A 05/2015

PicoStar is a trademark of Texas Instruments.

NOTES:

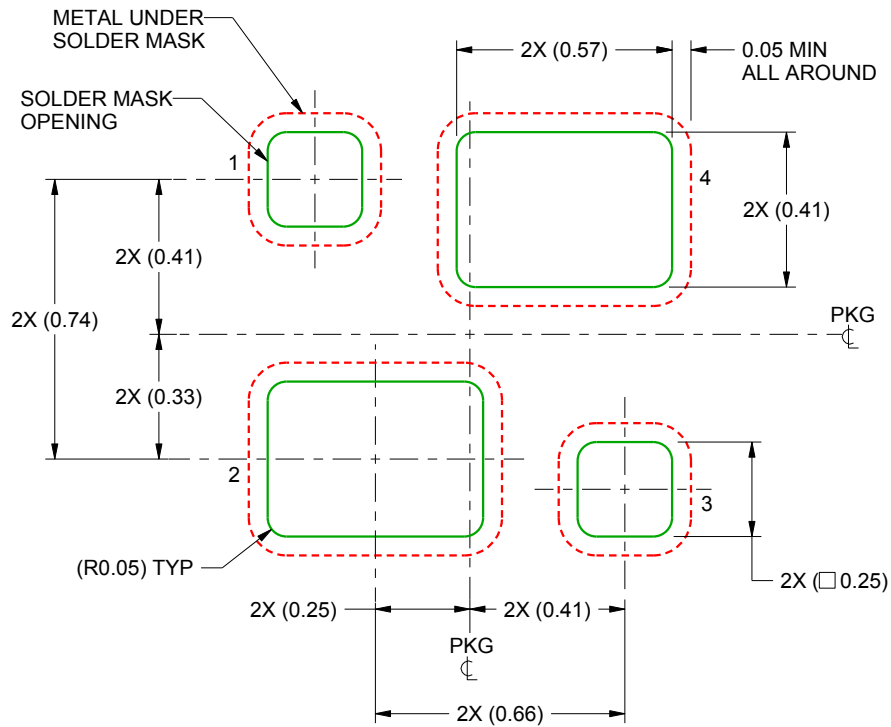
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M
2. This drawing is subject to change without notice.
3. This package is a Pb-free bump design. Bump finish may vary. To determine the exact finish, refer to the device datasheet or contact a local TI representative.

EXAMPLE BOARD LAYOUT

YME0004A

PicoStar™ - 0.22 mm max height

PicoStar™



LAND PATTERN EXAMPLE
SOLDER MASK DEFINED
SCALE:50X

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NOTES: (continued)

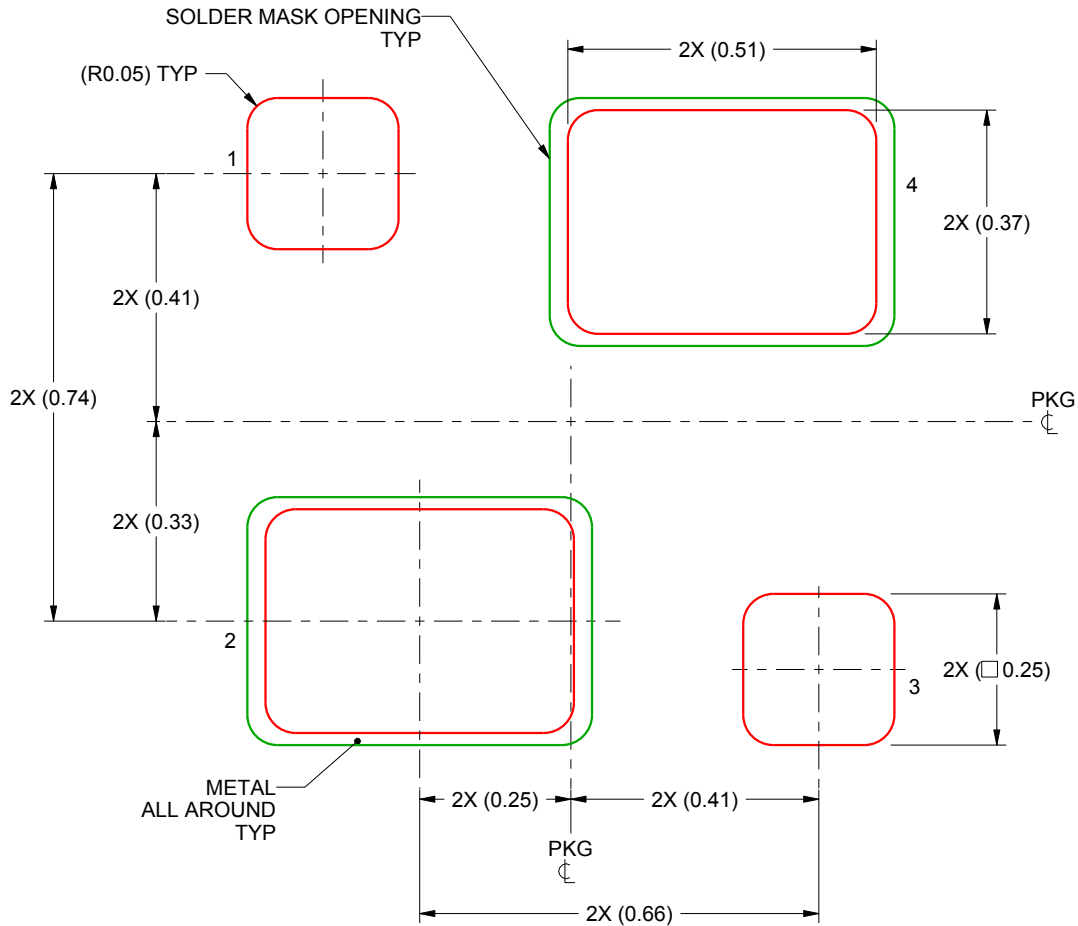
4. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

EXAMPLE STENCIL DESIGN

YME0004A

PicoStar™ - 0.22 mm max height

PicoStar™



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL

PADS 2 & 4
81% PRINTED ON SOLDER COVERAGE BY AREA
SCALE:80X

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NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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